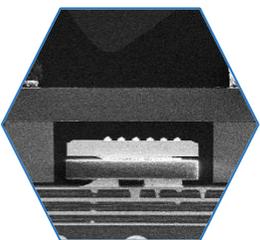
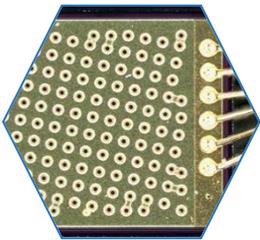
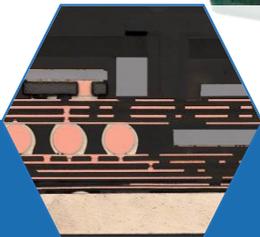


## STMicroelectronics Proximity Sensor and Flood Illuminator

*New time-of-flight and illumination device from the Apple iPhone 12.*



**Title:**  
STMicroelectronics  
Proximity Sensor  
and Flood  
Illuminator

**Pages:** 180

**Date:**  
June 2021

**Format:**  
PDF & Excel file

**Reference:**  
SPR21576

This full reverse costing study has been conducted to provide insights into technology data, the manufacturing cost and selling price of the STMicroelectronics Proximity Sensor and Flood Illuminator in the Apple iPhone 12.

Located in the front above the main speaker, the proximity sensor and flood illuminator use optical Land Grid Array (LGA) packaging. The device is a custom version for Apple, coming after STMicroelectronics also released a custom proximity sensor for the iPhone X. While being 15% smaller than the previous version overall, the new version's flood illuminator is twice as large. The sensor is still based on FlightSense™ technology.

The flood illuminator has a larger Vertical Cavity Surface Emitting Laser (VCSEL) die and VCSEL driver die. The diffuser is more sophisticated with a complexity close to a diffractive optical element.

To reduce the package size with larger components, STMicroelectronics has developed a 3D package with two stacked Printed Circuit Boards (PCBs). The 3D package manages the heat dissipation of the flood VCSEL thanks to a ceramic substrate, solder balls and PCB design.

This report analyzes the complete microsystem from the VCSEL illuminator of the proximity sensor manufactured by Trumpf to the VCSEL of the flood illuminator manufactured by Lumentum. It also analyzes the two integrated circuits with VCSEL driver from Texas Instruments and the Single Photon Avalanche Diode (SPAD) developed by STMicroelectronics.

It includes analyses of the package, the diffuser and the filters with optical and Scanning Electron Microscopy pictures and Energy Dispersive X-ray analyses of the main semiconductor components. The report also includes a complete cost analysis and price estimation of the device based on a detailed description of the package, the Time-of-Flight detector, and the two VCSELs.

The report features also a complete technology comparison with the proximity sensor from the Apple iPhone X.

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The report features also a complete technology comparison with the proximity sensor from the Apple iPhone X.

### COMPLETE TEARDOWN WITH

- Explanation of device operation
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- Materials analysis
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## AUTHORS



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*Léo VATANT works as a microelectronic laboratory analyst at System Plus Consulting. He is graduated from the University of Limoges where he obtained a Master degree in material science majoring Ceramics. He previously worked on different subject among which solar cells and tellurite glasses for optical fibre application."*

## RELATED REPORTS



### 3D Time-of-Flight Module in Meizu 17 Pro

*The first 3D ToF camera from Samsung with Lumentum's VCSEL.*

November 2020



### Smartphone Design Win Quarterly Monitor

*The first-ever smartphone technology monitor covering the latest components, packaging, and silicon chip choices of smartphone makers.*

April 2021

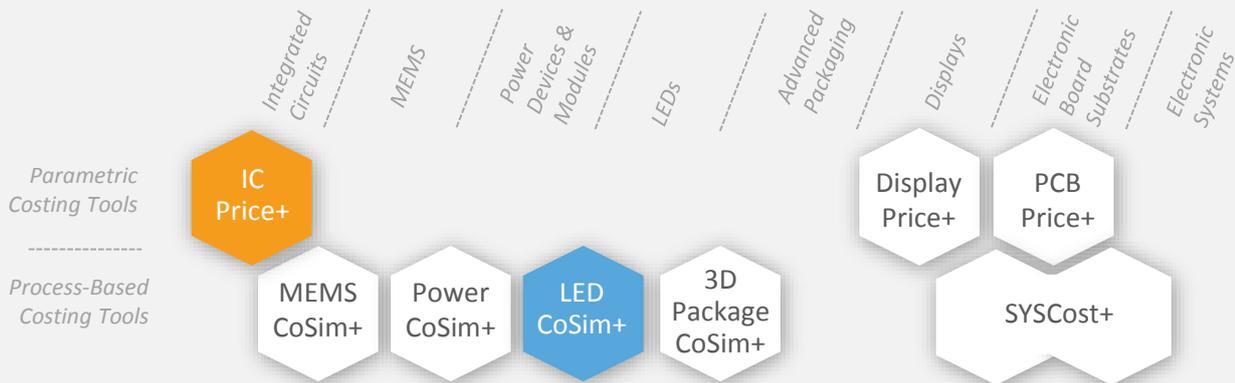


### 3D Imaging & Sensing 2020

*While a second wave of 3D sensing technology integration has been initiated by Android phones, could Time-of-Flight be the decisive technology for future consumer applications?*

February 2020

## COSTING TOOLS



Our analysis is performed with our costing tools LED CoSim+ and IC Price+.

System Plus Consulting offers powerful costing tools to evaluate any process or device, the production cost and selling price, from single chip to complex structures. All these tools are on sale under corporate license.

### LED CoSim+

The process-based costing tool is used to evaluate the manufacturing cost per wafer using your own inputs or using the predefined parameters included in the tool. It is possible to enter any LED process flow.

### IC Price+

The tool performs the necessary cost simulation of any Integrated Circuit: ASICs, microcontrollers, DSP, memories, smartpower...

## ABOUT SYSTEM PLUS CONSULTING

System Plus Consulting is specialized in the cost analysis of electronics from semiconductor devices to electronic systems. A complete range of services and costing tools to provide in-depth production cost studies and to estimate the objective selling price of a product is available.

Our services:

- **STRUCTURE & PROCESS ANALYSES**
- **TEARDOWNS**
- **CUSTOM ANALYSES**
- **COSTING SERVICES**
- **COSTING TOOLS**
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## WHAT IS A REVERSE COSTING®?

Reverse Costing® is the process of disassembling a device (or a system) in order to identify its technology and calculate its manufacturing cost, using in-house models and tools.



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# TERMS AND CONDITIONS OF SALES

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## 1. INTRODUCTION

The present terms and conditions apply to the offers, sales and deliveries of services managed by System Plus Consulting except in the case of a particular written agreement.

Buyer must note that placing an order means an agreement without any restriction with these terms and conditions.

## 2. PRICES

Prices of the purchased services are those which are in force on the date the order is placed. Prices are in Euros and worked out without taxes. Consequently, the taxes and possible added costs agreed when the order is placed will be charged on these initial prices.

System Plus Consulting may change its prices whenever the company thinks it necessary. However, the company commits itself in invoicing at the prices in force on the date the order is placed.

## 3. REBATES and DISCOUNTS

The quoted prices already include the rebates and discounts that System Plus Consulting could have granted according to the number of orders placed by the Buyer, or other specific conditions. No discount is granted in case of early payment.

## 4. TERMS OF PAYMENT

System Plus Consulting delivered services are to be paid within 30 days end of month by bank transfer except in the case of a particular written agreement.

If the payment does not reach System Plus Consulting on the deadline, the Buyer has to pay System Plus Consulting a penalty for late payment the amount of which is three times the legal interest rate. The legal interest rate is the current one on the delivery date. This penalty is worked out on the unpaid invoice amount, starting from the invoice deadline. This penalty is sent without previous notice.

When payment terms are over 30 days end of month, the Buyer has to pay a deposit which amount is 10% of the total invoice amount when placing his order.

## 5. OWNERSHIP

System Plus Consulting remains sole owner of the delivered services until total payment of the invoice.

## 6. DELIVERIES

The delivery schedule on the purchase order is given for information only and cannot be strictly guaranteed. Consequently any reasonable delay in the delivery of services will not allow the buyer to claim for damages or to cancel the order.

## 7. ENTRUSTED GOODS SHIPMENT

The transport costs and risks are fully born by the Buyer. Should the customer wish to ensure the goods against lost or damage on the base of their real value, he must imperatively point it out to System Plus Consulting when the shipment takes place. Without any specific requirement, insurance terms for the return of goods will be the carrier current ones (reimbursement based on good weight instead of the real value).

## 8. FORCE MAJEURE

System Plus Consulting responsibility will not be involved in non execution or late delivery of one of its duties described in the current terms and conditions if these are the result of a force majeure case. Therefore, the force majeure includes all external event unpredictable and irresistible as defined by the article 1148 of the French Code Civil?

## 9. CONFIDENTIALITY

As a rule, all information handed by customers to system Plus Consulting are considered as strictly confidential.

A non-disclosure agreement can be signed on demand.

## 10. RESPONSABILITY LIMITATION

The Buyer is responsible for the use and interpretations he makes of the reports delivered by System Plus Consulting. Consequently, System Plus Consulting responsibility can in no case be called into question for any direct or indirect damage, financial or otherwise, that may result from the use of the results of our analysis or results obtained using one of our costing tools.

## 11. APPLICABLE LAW

Any dispute that may arise about the interpretation or execution of the current terms and conditions shall be resolved applying the French law.

If the dispute cannot be settled out-of-court, the competent Court will be the Tribunal de Commerce de Nantes.